

Amendments

In the claims

Please replace pending claim 48 with new claim 48 as follows.

48. (Once Amended) A method of mounting a plurality of spring contact elements to an electronic component, comprising:

providing a plurality of elongate spring contact elements, each having a base end, a contact end, and a central body portion therebetween; and

mounting the base ends of the spring contact elements to corresponding terminals on the electronic component, the contact ends of the spring contact elements extending about the surface of the electronic component and the body portion being spaced from the electronic component.

Please add new claims 54-68 as follows:

54. (New) Method of making comprising steps of:

fabricating a contact element on a sacrificial substrate;

mounting said contact element to an electronic component; and

releasing said contact element from said sacrificial substrate.

55. (New) The method of claim 54, wherein said electronic component comprises a terminal, and said step of mounting comprises attaching said contact element to said terminal.

56. (New) The method of claim 54, wherein said electronic component comprises a stud, and said step of mounting comprises attaching said contact element to said stud.

57. (New) The method of claim 54, wherein said step of fabricating comprises:
forming a masking layer on said sacrificial substrate; and
depositing contact element material in an opening in said masking layer.

58. (New) The method of claim 54, wherein said step of fabricating comprises:
forming a trench in said sacrificial substrate, said trench defining a contour of said
contact element.

59. (New) The method of claim 58, wherein said step of forming a trench further
comprises:

forming a plurality of said trenches configured such that said contour is multilevel.

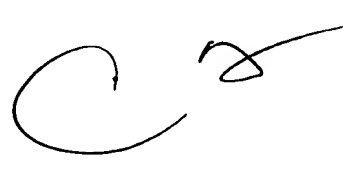
60. (New) The method of claim 59, wherein said multilevel contour comprises a first
level and a second level, said first level defining a body portion of said contact element, and
said second level defining a contact portion of said contact element.

61. (New) The method of claim 59, wherein said step of forming a trench further
comprises forming a depression in one of said trenches, said depression defining a tip feature
of said contact element.

62. (New) The method of claim 54, wherein said contact element comprises a base
portion and a contact portion, and wherein said step of mounting comprises attaching said
base portion to said electronic component.

63. (New) The method of claim 62, wherein said contact element further comprises a
body portion disposed between said base portion and said contact portion such that said
contact portion is spaced away from said electronic component after said base portion is
attached to said electronic component.

64. (New) The method of claim 54, wherein said step of mounting is performed prior
to said step of releasing.



65. (New) The method of claim 54, wherein:
said step of fabricating further comprises fabricating a plurality of said contact elements on said sacrificial substrate;
said step of mounting further comprises mounting said plurality of contact elements on said electronic component; and
said step of releasing further comprises releasing said plurality of contact elements from said sacrificial substrate.

66. (New) The method of claim 65, wherein said step of fabricating a plurality of said contact elements comprises forming a plurality of trenches in said sacrificial substrate, said plurality of trenches defining contours of said contact elements.

67. (New) The method of claim 66, wherein said plurality of trenches are configured such that said contours are multilevel.

68. (New) The method of claim 67, wherein each said multilevel contour comprises a first level and a second level, said first level defining a body portion of one of said contact elements, and said second level defining a contact portion of said one of said contact elements.

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Concluded